

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1tc1504cs8-3.3#pbf

(Engineering Calculation)

SOIC

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**TOTAL MASS (g) : 0.075096**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003263	1000000	43451.1328125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023653	975000	314970.78125		
		Iron (Fe)	7439-89-6	0.000582	24000	7750.09472656		
		Phosphorus (P)	7723-14-0	0.000007	300	93.2142028809		
		Zinc (Zn)	7440-66-6	0.000017	700	226.377349854		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.024259</b>	<b>1000000</b>	<b>323040.46875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001477	1000000	19666.2246094		
		<b>External Plating Total:</b>				<b>0.001477</b>	<b>1000000</b>	<b>19666.2246094</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000194	1000000	2583.36499023		
<b>Internal Plating Total:</b>				<b>0.000194</b>	<b>1000000</b>	<b>2583.36499023</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000957	750000	12743.7128906		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000319	250000	4247.90429688		
<b>Die Attach Total:</b>				<b>0.001276</b>	<b>1000000</b>	<b>16991.6171875</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006657	150000	88646.703125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.036392	820000	484607.3125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001110	25000	14781.1083984		
		Carbon Black (C)	1333-86-4	0.000222	5000	2956.22192383		
		<b>Encapsulation Total:</b>				<b>0.044381</b>	<b>1000000</b>	<b>590991.3125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000246	1000000	3275.81347656		
					<b>TOTAL MASS (g) :</b>	<b>0.075096</b>		